

Claims

- [c1] 1. A heat exchanger mounting assembly for mounting a heat exchanger in thermal contact with an electronic device mounted to a circuit board, comprising: a plurality of anchors mountable on the circuit board about the electronic device; a clamping wire including a center section having torsional spring properties and extending from each end thereof a end each having a hooked end, the ends being resiliently flexible about the long axis of the center section, the clamping wire being mountable over a heat exchanger with each hooked end flexed down and engaged to an anchor on the circuit board.
- [c2] 2. A heat exchanger mounting assembly of claim 1 wherein the heat exchanger includes an upper surface channel and the center section of the wire is selected to fit into the upper surface channel.
- [c3] 3. A heat exchanger comprising: a body including (i) a base portion including a thermally coupleable surface, the thermally coupleable surface capable of thermal coupling to a heat conductor and defining a plane; (ii) a heat exchanger fluid passage thermally coupled to the base portion through which a heat exchanging fluid may be

circulated so that heat can be transferred between the heat exchanging fluid and the body; (iii) an inlet to the fluid passage and (iv) an outlet from the fluid passage and wherein the base has a thickness measured orthogonal to the plane defined by the thermally coupleable surface which increases and then decreases along at least one plane orthogonally through thermally coupleable surface.

- [c4] 4. The heat exchanger of claim 3 wherein the fluid passage is distanced substantially uniformly from the thermally coupleable surface capable along the at least one plane.
- [c5] 5. The heat exchanger of claim 3 wherein along the at least one plane the direct thermal path distance between any part of the fluid passage and the thermally coupleable surface is no greater than 2.5 times the direct thermal path distance between any other part of the fluid passage and the thermally coupleable surface.
- [c6] 6. The heat exchanger of claim 3 wherein the base is pyramidal, triangularly prismatic or frustum including a bottom surface and at least one upper surface and the thermally coupleable surface is exposed on the bottom surface.

- [c7] 7.The heat exchanger of claim 3 wherein the base includes a core portion including the thermally coupleable surface and formed of a first thermally conductive material and a surrounding portion thermally coupled to the core portion and formed of a second thermally conductive material.
- [c8] 8.The heat exchanger of claim 3 wherein the thickness of the base decreases towards its side edges.